

AMENDMENT

In The Claims

Please amend the claims as follows:

1. (Twice Amended) A wafer carrier for supporting a substrate, comprising:
a circular plate having a flat edge region extending around the circumference of said plate;

and

B' a circular recessed center region having a recessed bottom surface and including an upwardly inclined surface around the periphery of said recessed bottom surface,

wherein the substrate is supported by a portion of the upwardly inclined surface and is spaced apart from said recessed bottom surface such that the substrate is supported by said wafer carrier only around the entire periphery edge of the substrate, and wherein said wafer carrier is comprised of a material having a coefficient of thermal expansion in the range of 2.6×10^{-6} to $5 \times 10^{-6}/^{\circ}\text{C}$.

Please cancel Claim 7 without prejudice to Applicants' rights to pursue the subject matter thereof in one or more divisional, continuation, or continuation-in-part applications.

REMARKS

Claims 1-12 are pending in the instant application. Claims 1, 2, and 7-9 stand rejected under 35 U.S.C. § 102(e) as being anticipated by U.S. Patent No. 5,891,251 to MacLeish *et al.* ("MacLeish *et al.*"); Claims 3-6, and 10-12 stand rejected under 35 U.S.C. § 103(a) as being obvious over MacLeish *et al.*; Claims 3-12 stand rejected under 35 U.S.C. § 103(a) as being obvious over MacLeish *et al.* in view of U.S. Patent No. 5,837,058 to Chen *et al.* ("Chen *et al.*").

Claim 1 has been amended, support for which is found in originally filed Claim 7 and in the specification at page 5, lines 25 to 33. No new matter is presented by the amendment to Claim 1, and entry thereof is appropriate and respectfully requested. Claim 7 has been cancelled without prejudice or disclaimer. After entry of the present amendment, Claims 1-6, and 8-12 will be pending for further examination. A copy of the pending claims, after entry of the present amendment, is attached hereto for the Examiner's convenience.